# Hybrid 6p26 Traveler

April 13, 2000

## 1 Connectivity

Repairs on shorts:
Fixes for opens:

## 2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 6P26 has die: 011-034 115-029 114-050 114-004 114-005 114-006

## 3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

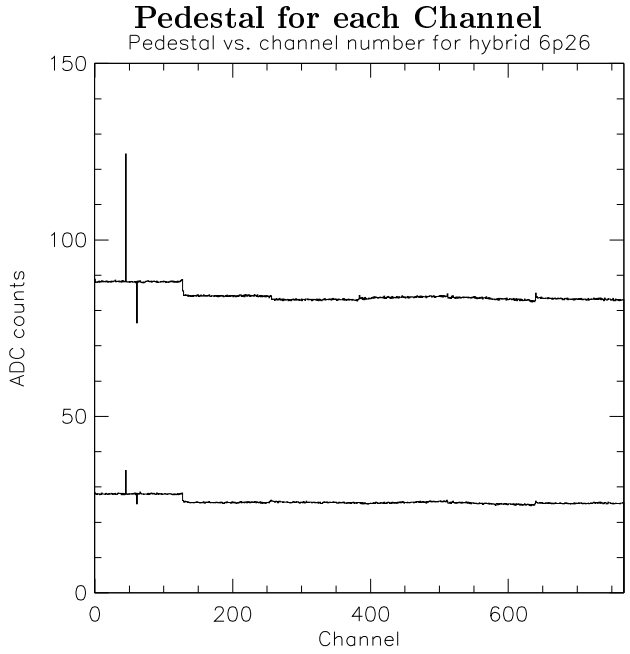
```
% Hybrid 6p26 classification info. Created 09:38:26 04/13/00

Hybrid 6p26 quality: fair
Chip classification: fair good good good good good
Bad channels (chip-channel): 0-45 0-61
Bad cells: none
Random bad capacitors: none
Channels at pedestal needed for DCMS: 35.8 36.7 38.6 34.6 34.8 37.3
```

## 4 Comments

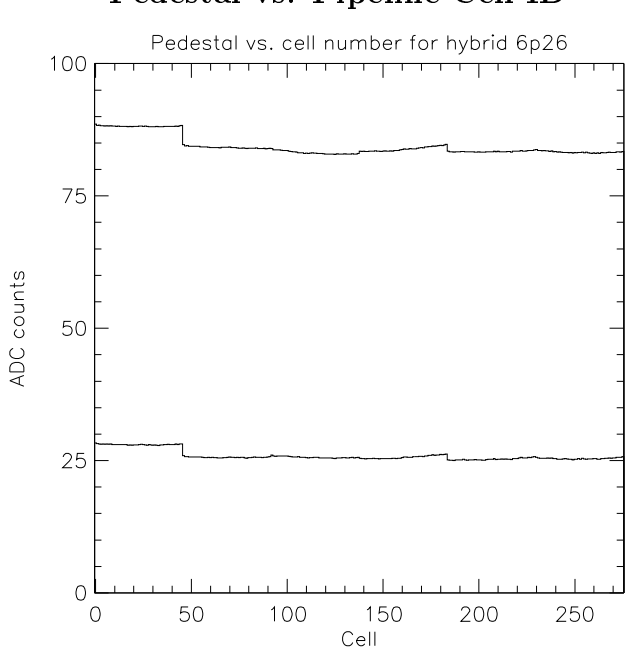
Bus7B open in the cable, fixed with a wire. BN open in cable, fixed with wire. Encapsulated. HV tested. Au FE DVDD and DGND wirebonds.

# 5 Pedestal

The following plot shows the pedestals vs. channel number with and without charge injection:



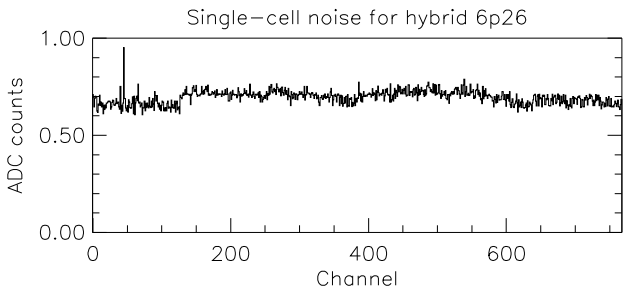

The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

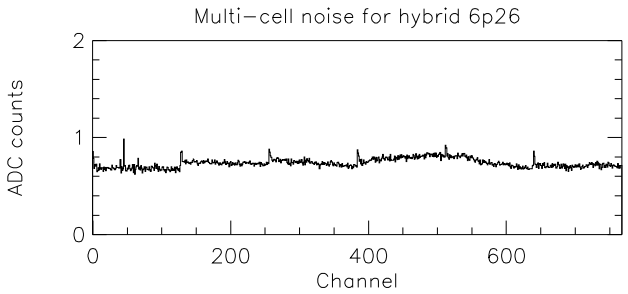


# 6 Noise

The following plots show the single-cell and multi-cell RMS noise:

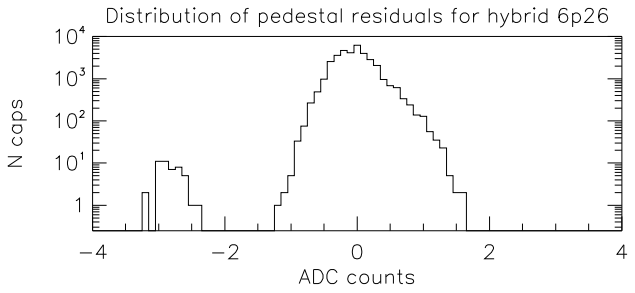
**RMS Noise**

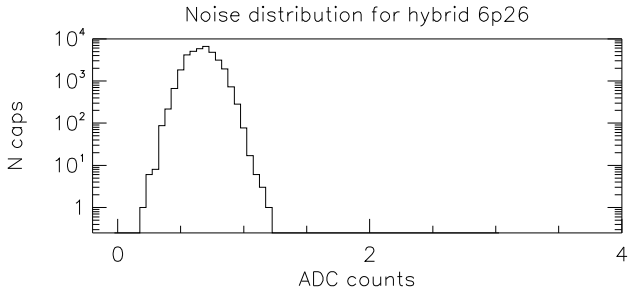


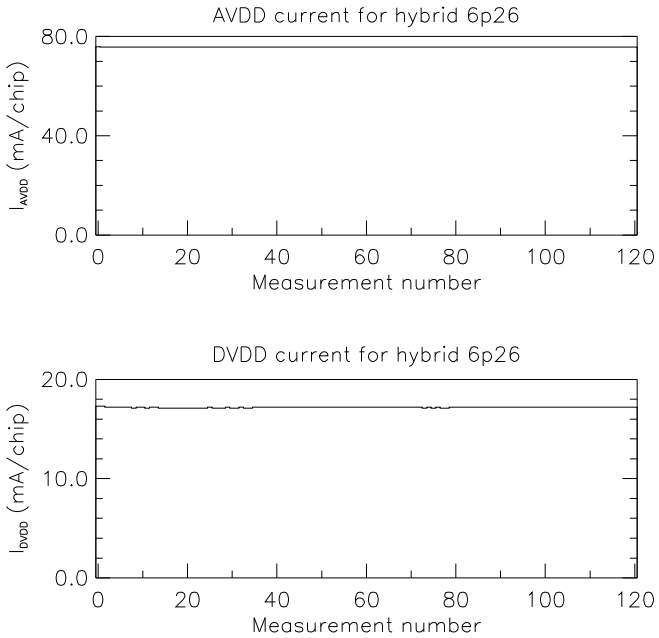

The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

**Distribution of Pedestals and Noise**



# 7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

**Supply Currents During Burn-in**